503530460 10/20/2015 PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIGNMENT	NEW ASSIGNMENT				
NATURE OF CONVEYANCE:		ASSIGNMENT					
CONVEYING PARTY	/ DATA						
		Name	Execution Date				
SIEMENS AKTIENGE	ESELLSCHAF	Т	10/17/2015				
RECEIVING PARTY	DATA						
Name:	EPCOS /	١G					
Street Address:	StMartir	StMartin-Strasse 53					
City:	Muenche	Muenchen					
State/Country:	GERMAN	GERMANY					
Postal Code:	81669	81669					
PROPERTY NUMBE	RS Total: 3						
Property Type		Number					
Patent Number:		057222					
Patent Number: 6		310420					
Patent Number: 6		136175					
		70,700,0010					
Fax Number:	•	72)732-9218 he e-mail address first; if that is :	unsuccessful it will be sent				
		if that is unsuccessful, it will be					
Phone:	97	72-732-1001					
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•		_ATER & MATSIL, L.L.P.					
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SIGNATURE:		/Ava Chuang/					
DATE SIGNED:		10/20/2015	10/20/2015				
Total Attackments 1							
Total Attachments: 1							

ASSIGNMENT

For a good and valuable consideration, the receipt of which is thereby acknowledged, the undersigned

Siemens Aktiengesellschaft, a corporation having its principal office in Munich, Germany,

hereby sell, assign and transfer to

EPCOS AG, a corporation having its principal office at St.-Martin-Str. 53, 81669 Munich, Germany,

and to its successors, assigns and legal representatives, the entire right, title and interest in and to said U.S. Patent Applications / U.S. Patents:

Title	Country	Serial No.	Filing date	Patent No	Issue Date
Method for the Production of Flip-Chip Mounting- Ready Contacts of Electrical Components	US	09/103,163	06/22/1998	6,057,222	05/02/2000
Electrical Component in Particular an SAW Component Operating with Surface Acoustic Waves and a Method for Its Production	US	09/103,158	06/22/1998	6,310,420	10/30/2001
Method of Producing an Electronic Component, in particular a Surface Acoustic Wave Component	US	09/103,160	06/22/1998	6,136,175	10/24/2000

Date: Munich, 17.10.2015

Siemens Aktiengesellschaft

<u>1. 101</u>14 2. C. Ruman

Name: Renner Klinger Position: Authorized Officers

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RECORDED: 10/20/2015